How to write a technical paper for the IEEE?

Lukács Eszter

Client Services Manager Europe





About the IEEE

- World's largest technical membership association with more than 430,000 members in over 160 countries
- Not for profit organization "Advancing Technology For Humanity"
- Four Core areas of activity
 - Membership organization
 - Conferences organizer
 - Standards developer
 - Publisher of journals, conferences, standards, ebooks and elearning
- IEEE Xplore by the numbers:
 - Nearly 4 million total documents
 - Over 3 million unique users
 - More than 8 million downloads per month
 - 15 year anniversary in 2015!



IEEE student volunteers in Mumbai



IEEE Day Contest Winner, Colombia



Why you should rely on IEEE information



Full text access to IEEE/IET Electronic Library (IEL)

- Nearly four million full text documents
- 179 IEEE journals & magazines
- 1400+ annual IEEE conferences + 43 VDE conferences
- More than 2800 IEEE standards (active, archived. redlines) + IEEE Standard Dictionary
- 20 IET conferences, 26 IET journals & magazines

- Bell Labs Technical Journal (BLTJ) back to 1922
- Backfile to 1988, select legacy data back to 1872
- Inspec index records for all articles



IEEE quality makes an impact

Thomson Reuters Journal Citation Reports® by Impact Factor

IEEE publishes:

- 17 of the top 20 journals in Electrical and Electronic Engineering
- 14 of the top 15 journals in Telecommunications
- 3 of the top 5 journals in Computer Science, Hardware & Architecture
- 3 of the top 5 journals in Computer Science, Cybernetics
- **3 of the top 5** journals in Automation & Control Systems
- **3 of the top 5** journals in Artificial Intelligence
- 2 of the top 5 journals in Imaging Science & Photographic Technology

The Thomson Reuters Journal Citation Reports presents quantifiable statistical data that provides a systematic, objective way to evaluate the world's leading journals.

Based on the 2015 study released June 2016

More info: www.ieee.org/citations

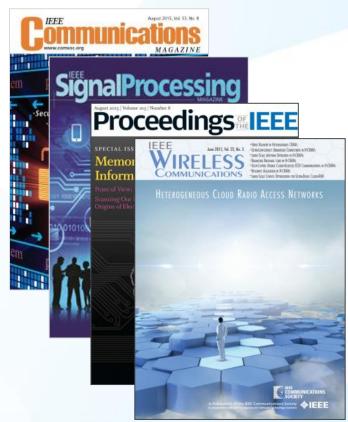


IEEE quality makes an impact

Thomson Reuters Journal Citation Reports® by Impact Factor

IEEE journals are:

- # 1 in Automation and Control
- # 1 in Artificial Intelligence
- # 1 in Computer Hardware
- # 1 in Cybernetics
- # 1 in Information Systems
- # 1 in Manufacturing Engineering
- # 1 in Theory and Methods
- # 1 in Telecommunications
- # 2 in Electrical Engineering
- # 3 in Aerospace Engineering



The Thomson Reuters Journal Citation Reports presents quantifiable statistical data that provides a systematic, objective way to evaluate the world's leading journals.



IEEE and Patents



IEEE research powers new patents



Analysis of Patent Referencing to IEEE Papers, Conferences, and Standards 1997-2014

Report prepared for:

Institute of Electrical and Electronic Engineers
445 Hoes Lane
Piscatures, NJ 08355, USA

Report prepared by:

1790 Analytics LLC 130 Haddon Avenue Haddonfield, NJ 08033 www.1290analytics.com

May 14, 2015

A study of the top 40 patenting organizations ranks IEEE #1 again

- Over three times more citations than any other publisher
- Patent referencing to IEEE increased 896% since 1997
- The importance of sci-tech literature in patents is rising
- IEEE research is increasingly valuable to innovators

1790 Analytics LLC performed an in-depth analysis of the science references from top patenting firms.

Source: 1790 Analytics LLC 2015



IEEE Leads US Patent Citations

Top 20 Publishers Referenced Most Frequently by Top 40 Patenting Organizations

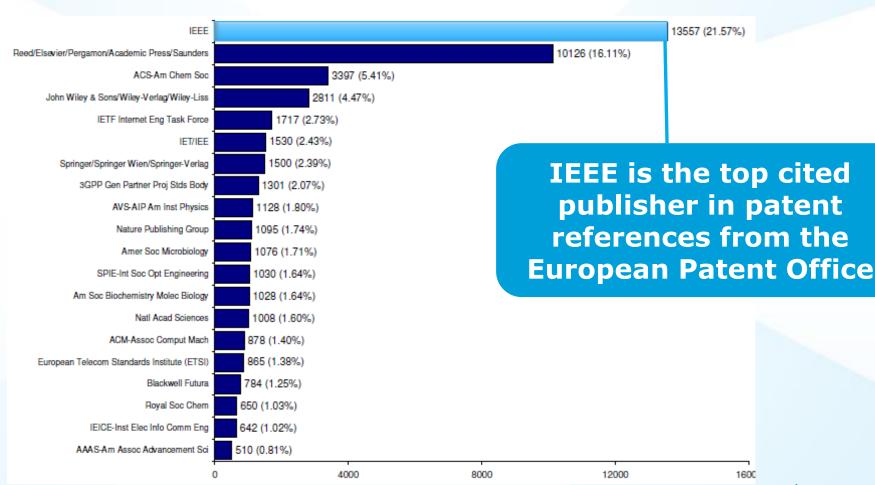


Source: 1790 Analytics LLC 2015. Based on number of references to papers/standards/conferences from 1997-2014



IEEE Leads European Patent Citations

Top 20 Publishers Referenced Most Frequently by Top 25 Patenting Organizations





Source: 1790 Analytics LLC 2012, , Science References from 1997-2011

Technology areas where patents cite IEEE most

Battery

Computer hardware

Computer software

Information storage

Measuring, testing, and control

Medical devices

Nuclear and X-ray

Optics

Power systems

Robotics

Semiconductors

Smart Grid

Solar/Photovoltaic

Telecommunications

Wind Energy

Source: 1790 Analytics LLC 2015



Content on IEEE Xplore Digital Library



Full text content from all 39 IEEE Societies

IEEE Aerospace and Electronic Systems Society

IEEE Antennas and Propagation Society

IEEE Broadcast Technology Society

IEEE Circuits and Systems Society

IEEE Communications Society

IEEE Components, Packaging, and Manufacturing

Technology Society

IEEE Computational Intelligence Society

IEEE Computer Society

IEEE Consumer Electronics Society

IEEE Control Systems Society

IEEE Dielectrics and Electrical Insulation Society

IEEE Education Society

IEEE Electron Devices Society

IEEE Electromagnetic Compatibility Society

IEEE Engineering in Medicine and Biology Society

IEEE Geoscience and Remote Sensing Society

IEEE Industrial Electronics Society

IEEE Industry Applications Society

IEEE Information Theory Society

IEEE Instrumentation and Measurement Society

IEEE Intelligent Transportation Systems Society

IEEE Magnetics Society

IEEE Microwave Theory and Techniques Society

IEEE Nuclear and Plasma Sciences Society

IEEE Oceanic Engineering Society

IEEE Photonics Society

IEEE Power Electronics Society

IEEE Power & Energy Society

IEEE Product Safety Engineering Society

IEEE Professional Communications Society

IEEE Reliability Society

IEEE Robotics and Automation Society

IEEE Signal Processing Society

IEEE Society on Social Implications of Technology

IEEE Solid-State Circuits Society

IEEE Systems, Man, and Cybernetics Society

IEEE Technology and Engineering Management Society NEW in 2015

IEEE Ultrasonics, Ferroelectrics, and Frequency Control Society

IEEE Vehicular Technology Society



IEEE covers all areas of technology

More than just electrical engineering & computer science

MACHINE LEARNING BIG DATA

OPTICS RENEWABLE ENERGY

SEMICONDUCTORS SMART GRID

MAGING NANOTECHNOLOGY

SIGNAL PROCESSING AEROSPACE

COMMUNICATIONS

HUMAN-CENTERED INFORMATICS

BIOMEDICAL ENGINEERING

ELECTRONICS

NEXT GEN WIRELESS CIRCUITS

CLOUD COMPUTING

CYBER SECURITY ELECTROMAGNETICS & IEEE



Multidisciplinary Content on IEEE Xplore Digital Library



Life Sciences

- At least eight IEEE publications are dedicated in whole or in part to technology related to Life Sciences.
- Plus, there are more than 90 annual conferences, 20 periodicals and 20 IEEE standards that cover medical device communications.
- In IEEE *Xplore*, you'll also find coverage of therapeutic devices used in rehabilitation processes, such as physical therapy and devices used to restore movement and function.
- Examples of IEEE publications:
 - IEEE Pulse
 - IEEE Trans. on Biomedical Engineering
 - IEEE Reviews on Biomedical Engineering
 - IEEE Trans. on Neural Systems and Rehabilitation Engineering
 - IEEE Trans. on Information Technology in Biomedicine
 - IEEE Trans. on Medical Imaging
 - IEEE/ACM Trans. on Computational Biology and Bioinformatics
 - IEEE Trans. on Biomedical Circuits and Systems
 - IEEE Trans. on NanoBioscience
 - IEEE Trans. on Autonomous Mental Development.



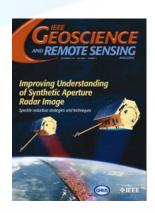






Geoscience and related fields

- IEEE's geoscience and remote sensing publications cover the fusion of engineering and geoscientific fields including geophysics, geology, hydrology, meteorology, etc.
- In IEEE Xplore, you'll also find information relevant to natural resources engineering and mineral resources engineering, including extensive coverage of technologies related to oil and gas exploration, drilling operations, offshore oil rigs and mining.



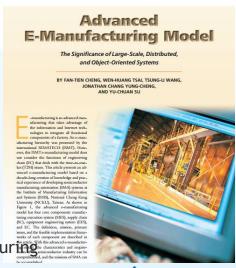
- Examples of IEEE publications:
 - IEEE Trans. on Geoscience & Remote Sensing
 - IEEE Geoscience & Remote Sensing Magazine
 - IEEE Geoscience & Remote Sensing Letters
 - IEEE International Symposium Geoscience and Remote Sensing (IGARSS)
 - IEEE Petroleum and Chemical Industry Technical Conference (PCIC)





Manufacturing Engineering

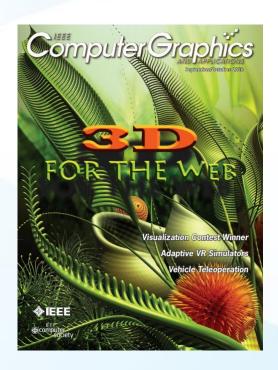
- IEEE's publications cover manufacturing practices and technologies, including the development of systems, processes, machines, and tools.
- In IEEE Xplore, you'll find information on virtual manufacturing, computer integrated manufacturing, agile manufacturing, quality control, robotics and automation, mechatronics, and much more
- Relevant IEEE publications include:
 - IEEE/ASME Transactions on Mechatronics
 (#1 most cited journal in Engineering Manufacturing)
 - IEEE Transactions on Components, Packaging and Manufacturing Technology
 - IEEE Transactions on Semiconductor Manufacturing
 - IEEE Transactions on Automation Science and Engineering
 - IEEE Robotics & Automation Magazine
 - IEEE International Symposium on Assembly and Manufacturing
 - International Conference on Digital Manufacturing and Automation
 - e-Manufacturing & Design Collaboration Symposium Electronics Manufacturing Technology Symposium
 - International Conference on System Science, Engineering Design and Manufacturing Informatization





Digital Art & Technology

- IEEE Xplore covers the leading edge of computer graphics technology and its applications in everything from business to the arts.
- Topics include computer graphics, design, animation, 3D, user interface, motion graphics, and more
- Examples of IEEE Xplore publications:
 - IEEE Computer Graphics
 - IEEE Trans. On Visualization & Computer Graphics
 - International Conference on Computer-Aided Design
 & Computer Graphics
 - International Conference on Computer Graphics,
 Imaging & Visualization
 - International Conference on Image & Graphics





Game Design

- IEEE Xplore covers the design of video games, mathematical games, human-computer interactions in games, and games involving physical objects.
- Topics include game production, computational intelligence, artificial intelligence, simulations, and more
- Examples of IEEE Xplore publications:
 - IEEE Trans. On Computational Intelligence and AI in Games
 - Symposium on Computational Intelligence in Games
 - International Conference on Computer Games
 - International Workshop on Digital Game and Intelligent Toy Enhanced Learning
 - International Symposium on Haptic, Audio, Visual Environments and Games

Computational Intelligence in Games 2014 August 26 – 29, Park Inn Hotel, Dortmund, Germany

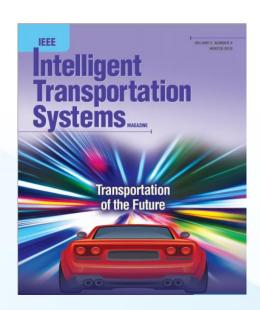




With IEEE Xplore, learn how technology impacts fields such as...

Transportation: intelligent transportation systems, logistics, supply chain management, and more

- Related IEEE Journals & Conferences:
 - IEEE Trans. on Intelligent Transportation
 Systems
 - IEEE Intelligent Transportation Systems
 Magazine
 - IEEE Trans. on Automation Science and Engineering
 - IEEE International Conference on Automation and Logistics





With IEEE *Xplore*, learn how technology impacts fields such as...

Business & Finance: information systems, project management, risk management, business informatics, R&D project selection and evaluation, IT investment justification, innovation, and more

Read articles by leaders in the field:



Prof. Clayton Christensen Harvard Business School

"Innovator's Dilemma" http://www.claytonchristensen.com/

Optimal Detection of Sparse Mixtures against a Given Null Distribution

T. Tony Cai and Yihong Wu, Member, IEEE,

Abstract—Detection of sparse signals arises in a wide range of modern scientific studies. The focus of a has been mainly on Gaussian unisture models. In this paper, we consider the detection problem under a general sparse misture model and obtain explicit expressions for the detection boundary under mild regularity conditions. Moreover, for Gaussian mult hypothesis, we establish the adaptive optimality of the higher criticism procedure for all sparse mixtures satisfying the ame conditions. In particular, the general results obtained in this paper recover and extend in a unified manner the previously known results on sparse detection far beyond the conventional Gaussian model and other exponential families.

Index Terms—Hypothesis testing, high-dimensional statistics, sparse mixture, higher criticism, adaptive tests, total variation, Hellinger distance.

I. INTRODUCTION

Detection of sparse mixtures is an important problem that α in order to achieve the desired false alarm and miss detection

according to Ray(α_i), representing the random voltages observed on the n channels. In the absence of noise, α_i 's are all equal to one, the nominal value; while in the presence of signal, exactly one of the α_i 's becomes a known value $\alpha > 1$. Denoting the uniform distribution on [n] by U_n , the goal is to test the following commettine hyrotheses:

$$H_0^{(n)}: \alpha_i = 1, i \in [n],$$
 (1)
v.s. $H_1^{(n)}: \alpha_i = 1 + (\alpha - 1)\mathbf{1}_{\{i=J\}}, J \sim U_n$.

Since the signal only appears once out of the n samples, in order for the signal to be distinguishable from noise, it is necessary for the amplitude α to grow with the sample size n (in fact, at least logarithmically). By proving that the log-likelihood ratio converges to a stable distribution in the large-n limit, Dobrushin [1] obtained sharp asymptotics of the smallest

Prof. Tony Cai

The Wharton School of the University of Pennsylvania

With IEEE *Xplore*, learn how technology impacts fields such as...

Entertainment: computer graphics, animation, 3D, digital motion pictures, laser projectors, and more

Bringing Physical Characters to Life

Akhil J. Madhani Walt Disney Imagineering R&D

Ray Tracing for the Movie 'Cars'

Per H. Christensen*

Julian Fong

David M. Laur

Dana Batali

Pixar Animation Studios



ABSTRACT

Abstract

At Disney, we are s to present these ch entertainment robot Disney in attraction: In this talk, I hope Disney. In particula distilled from Disne As examples of cha I discuss two newer the Disney theme

developed in conjur

and has made appe

This paper describes how we extended Pixar's RenderMan renderer with ray tracing abilities. In order to ray trace highly complex scenes we use multiresolution geometry and texture caches, and use ray differentials to determine the appropriate resolution. With this method we are able to efficiently ray trace scenes with much more geometry and texture data than there is main memory. Moviequality rendering of scenes of such complexity had only previously been possible with pure scanline rendering algorithms. Adding ray

texture cache keeps recently accessed texture tiles ready for fast access. This combination of ray differentials and caching makes ray tracing of very complex scenes feasible.

This paper first gives a more detailed motivation for the use of ray tracing in 'Cars', and lists the harsh rendering requirements in the movie industry. It then gives an overview of how the REYES algorithm deals with complex scenes and goes on to explain our work on efficient ray tracing of equally complex scenes. An explanation of our hybrid rendering approach, combining REYES with ray tracing, follows. Finally, was measure the efficiency of our method on a





New IEEE Journals Planned for 2017

In 2017, IEEE will introduce six new journals that will be available for subscription:

- IEEE Communications Standards Magazine
- IEEE Journal of Electromagnetics, RF and Microwaves in Medicine and Biology
- IEEE Transactions on Emerging Topics in Computational Intelligence
- IEEE Transactions on **Green Communications and Networking**
- IEEE Transactions on Radiation and Plasma Medical Sciences
- IEEE Journal of Radio Frequency Identification
 - All Included in an IEL Subscription







New IEEE Journals Coming in 2016

In 2016, IEEE will introduce four new journals that will be available for subscription:

- IEEE Transactions on Intelligent Vehicles
- IEEE Journal on Multiscale and Multiphysics Computational Techniques
- IEEE Robotics and Automation Letters
- IEEE Transactions on Sustainable Computing



All included in an IEL subscription

For a complete title listing, to go: http://ieeexplore.ieee.org/xpl/opacjrn.jsp



New IEEE Journals from 2015

- IEEE Trans. on **Big Data**
- IEEE Trans. on Transportation Electrification
- IEEE Trans. on Cognitive Communications and Networking
- IEEE Trans. on Computational Imaging
- IEEE Trans. on Molecular, Biological, and Multi-Scale Communications
- IEEE Trans. on Multi-Scale Computing **Systems**
- IEEE Trans. on **Signal and Information Processing over Networks**
- IEEE Systems, Man, and Cybernetics Magazine

All included in an IEL subscription

For a complete title listing, to go: http://ieeexplore.ieee.org/xpl/opacjrn.jsp









A sampling of some of the new conferences added in 2015

- Big Data Software Engineering (BIGDSE), 2015 IEEE/ACM 1st International Workshop on
- Computational Electromagnetics (ICCEM), 2015 IEEE International Conference on
- DC Microgrids (ICDCM), 2015 IEEE First International Conference on
- Electromagnetic Compatibility and Signal Integrity, 2015 IEEE Symposium on
- Identity, Security and Behavior Analysis (ISBA), 2015 IEEE International Conference on
- Industrial Engineering and Operations Management (IEOM), 2015 International Conference on
- Microwaves for Intelligent Mobility (ICMIM), 2015 IEEE MTT-S International Conference on

- Multimedia Big Data (BigMM), 2015 IEEE International Conference on
- Networking Systems and Security (NSysS), 2015 International Conference on
- Sampling Theory and Applications (SampTA), 2015 International Conference on
- Signal Processing, Informatics, Communication and Energy Systems (SPICES), 2015 IEEE International Conference on
- Smart Cities Conference (ISC2), 2015 IEEE First International



Examples of New IEEE Conferences in 2014



- Internet of Things (WF-IoT), 2014 IEEE World Forum on
- Humanitarian Technology Conference, (IHTC), 2014 IEEE Canada International
- Aerospace Electronics and Remote Sensing Technology (ICARES), 2014 IEEE International Conference on
- Antenna Measurements & Applications (CAMA), 2014 IEEE Conference on
- Consumer Electronics, Taiwan (ICCE-TW), 2014 IEEE International Conference on
- **Energy Conversion** (CENCON), 2014 IEEE Conference on
- Ethics in Science, Technology and Engineering, 2014 IEEE International Symposium on

- Transportation Electrification Asia-Pacific (ITEC Asia-Pacific), 2014 IEEE Conference and Expo
- **Intelligent Energy** and Power Systems (IEPS), 2014 IEEE International Conference on
- **Quantum Optics Workshop** (QOW), 2014
- Sensor Systems for a Changing Ocean (SSCO), 2014 IEEE
- Wireless and Mobile, 2014 IEEE Asia Pacific Conference on
- Industrial Engineering and Information Technology (IEIT), 2014 International Conference on
- Guidance, Navigation and Control Conference (CGNCC), 2014 IEEE Chinese



Popular IEEE Standards

IEEE 802 Series—IEEE Standard for Ethernet

IEEE 3000 Standards Collection™—Formerly the IEEE Color Books®, this collection will reorganize the 13 Color Books into approximately 70 "dot" standards covering specific technical topics on all facets of industrial and commercial power systems.

IEEE 81-2012™—IEEE Guide for Measuring Earth Resistivity, Ground Impedance, and Earth Surface Potentials of a Grounding System

2012 National Electrical Safety Code® (NESC®)—Sets the ground rules for practical safeguarding of persons during the installation, operation, or maintenance of electric supply and communications lines and associated equipment.

IEEE 43™—IEEE Recommended Practice for Testing Insulation Resistance of Electric Machinery

IEEE 80™—IEEE Guide for Safety in AC Substation Grounding

IEEE 81™—IEEE Guide for Measuring Earth Resistivity, Ground Impedance, and Earth Surface Potentials of a Grounding System



Why Publish with the IEEE?



Increasing Scholarly Output



What sustains a university and its engineering school?



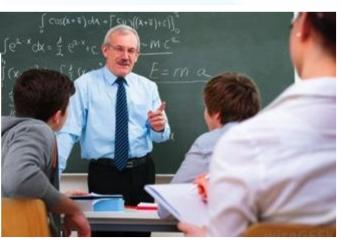
Enabling researchers to publish drives all of these essentials and helps an institution thrive

Published faculty is the key

- Benefit to Institution: Having a highly-published faculty has many benefits. It brings attention & prestige to the institution as cutting-edge research advancements are associated with the university. All of this can facilitate continued funding and higher enrollments.
- Benefit to Faculty: A sustainable, tenured career in academia as well as a higher profile in the field can be huge motivators for faculty to publish.









Publishing creates value

for your institution

for your faculty

for your investors and donors

for science & technology

for students



What else increases an IEEE author's visibility?

IEEE's relationships with indexing and abstracting providers



















Publish

IEEE journal or IEEE conference?

- A journal article is a fully developed presentation of your work and its final findings
 - Original research results presented
 - Clear conclusions are made and supported by the data
- A conference article can be written while research is ongoing
 - Can present preliminary results or highlight recent work
 - Gain informal feedback to use in your research
- Conference articles are typically shorter than journal articles, with less detail and fewer references



Publish

IEEE journal or IEEE conference?

IEEE Journals



 IEEE journals are cited 3 times more often in patent applications than other leading publisher's journals

CON

A high percentage of articles submitted to any professional publication are rejected

IEEE Conferences

- IEEE Conference
 proceedings are recognized
 worldwide as the most vital
 collection of consolidated
 published articles in EE,
 computer science, related
 fields
- Per IEEE Policy, if you do not present your article at a conference, it may be suppressed in IEEE Xplore and not indexed in other databases

Duplicate Publication

- IEEE's policy on duplicate publication states
 - "authors should only submit original work that has neither appeared elsewhere for publication, nor which is under review for another refereed publication. If authors have used their own previously published work(s) as a basis for a new submission, they are required to cite the previous work(s) and very briefly indicate how the new submission offers substantively novel contributions beyond those of the previously published work(s)."



Choose

Find periodicals in IEEE Xplore®

Browse by **Title** or **Topic** to find the periodical that's right for your research

Browse Journals & Magazines





Automatic Control, IEEE Transactions on









Popular

Early Access

Current Issue

Past Issues

About Journal

Submit Your Manuscript

About this Journal

Aims & Scope

Editorial Board

 IEEE Transactions on Automatic Control publication information

Content Announcements

- Innovative phased array antennas based on non-regular lattices and overlapped subarrays [call for papers]
- Special Issue on Manipulation, Manufacturing and Measurement on the Nanoscale









Aims & Scope

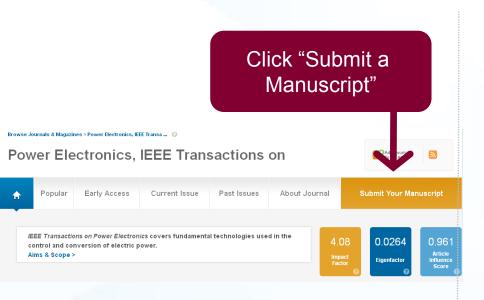
The theory, design and application of Control Systems. It shall encompass components, and the integration of these components, as are necessary for the construction of such systems. The word 'systems' as used herein shall be interpreted to include physical, biological, organizational and other entities and combinations thereof, which can be represented through a mathematical symbolism. The Field of Interest: shall include scientific, technical, industrial or other activities that contribute to this field, or utilize the techniques or products of this field, subject, as the art develops, to additions, subtractions, or other modifications directed or approved by the IEEE Technical Activities Board.

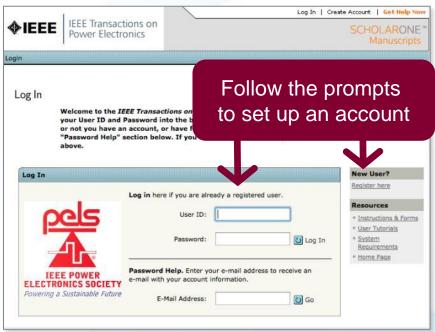
Persistent Link: http://ieeexplore.ieee.org/servlet/opac?punumber=9 More »



Submit

Journal paper submission is easy through *IEEE Xplore*®





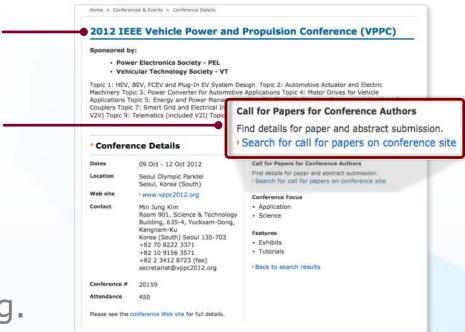


Submit

Use conference site (not IEEE Xplore) to submit to a conference

For complete information, see the Call for Papers for the conference in question.

Each IEEE sponsored conference has its own requirements for publishing.





IEEE conferences and events

Your search returned 289 Conferences for comput% from 2016-04-10

Notification of acceptance date: 11 Feb 2018

Conference Name ▲ ▼	Conference Date ▲ ▼	Location ▲ ▼
2019 IEEE Symposium on Security and Privacy (SP) Full Paper Submission deadline: 16 Nov 2018 Final submission deadline: 31 Mar 2019 Notification of acceptance date: 10 Feb 2019	19 May - 23 May 2019	Hyatt Regency San Francisco 5 Embarcadero Center San Francisco, CA, USA
2018 IEEE Frontiers in Education Conference (FIE) Abstract submission deadline: 05 Feb 2018 Full Paper Submission deadline: 23 Apr 2018 Final submission deadline: 09 Jul 2018 Notification of acceptance date: 21 May 2018	03 Oct - 06 Oct 2018	TBD TBD San Jose, CA, USA
2018 IEEE World Congress on Computational Intelligence (WCCI) Full Paper Submission deadline: 01 Feb 2018 Final submission deadline: 01 May 2018 Notification of acceptance date: 01 Apr 2018	08 Jul - 13 Jul 2018	Windsor Barra Convention Centre Rua Martinho de Mesquita Barra da Tijuca Rio de Janeiro, Brazil
2018 IEEE International Symposium on Information Theory (ISIT) Abstract submission deadline: 07 Jan 2018 Full Paper Submission deadline: 07 Jan 2018 Final submission deadline: 22 Apr 2018 Notification of acceptance date: 01 Apr 2018	17 Jun - 22 Jun 2018	Vail Cascade 1300 Westhaven Drive Vail, CO, USA
2018 IEEE Symposium on Security and Privacy (SP) Full Paper Submission deadline: 16 Nov 2017 Final submission deadline: 31 Mar 2018	20 May - 24 May 2018	Hyatt Regency San Francisco 5 Embarcadero Center San Francisco CA USA

IEEE

San Francisco, CA, USA

IEEE Electron Devices Society

http://eds.ieee.org/eds-meetings-calendars.html

Home :: Conferences :: Conferences Calendars

Number of Attendees: 100

Technical Conferences Calendars

Sort By: Date Location Title Abstract Submission Date Fi	ilter:
2016 International Symposium on VLSI Design, Automation and Test (VLSI-DAT Taiwan Number of Attendees: 300) Apr 25, 2016 - Apr 27, 2016
2016 International Symposium on VLSI Technology, Systems and Application (VLSI-TSA) Taiwan Number of Attendees: 400	Apr 25, 2016 - Apr 27, 2016
2016 5th International Symposium on Next-Generation Electronics (ISNE) Hsinchu, Taiwan Number of Attendees: 300	May 4, 2016 - May 6, 2016
2016 16th International Workshop on Junction Technology (IWJT) Shanghai, China	May 9, 2016 - May 10, 2016

Structure



Paper Structure

Elements of a manuscript

Title

Abstract

Keywords

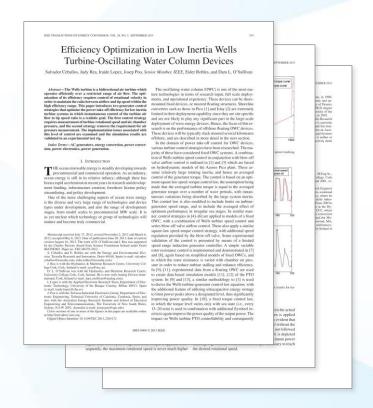
Introduction

Methodology

Results/Discussions/Findings

Conclusion

References





Paper Structure Title

An effective title should...

- •Answer the reader's question: "Is this article relevant to me?"
- •Grab the reader's attention
- •Describe the content of a paper using the fewest possible words
 - Is crisp, concise
 - Uses keywords
 - Avoids jargon





Paper Structure

Good vs. Bad Title

A Human Expert-based Approach to Electrical Peak Demand Management

VS

A better approach of managing environmental and energy sustainability via a study of different methods of electric load forecasting



Paper Structure

Good vs. Better Title

An Investigation into the Effects of Residential Air-Conditioning Maintenance in Reducing the Demand for Electrical Energy

VS

"Role of Air-Conditioning Maintenance on Electric Power Demand"



Paper Structure Abstract

Why you did A "stand alone" condensed version of the article No more than 250 words; What you did written in the past tense Uses keywords How the results and index terms were useful, important & move the field forward Why they're useful & important & move the field forward



Abstract:

http://eds.ieee.org/images/files/Publications/ted_info_for_authors.pdf

The abstract must be a **concise yet comprehensive reflection of what is in your article**. In particular, the abstract must be as follows.

- 1) Self-contained, without abbreviations, footnotes, or references; it should be a **microcosm of the full article**
- 2) Between **150-250 words**. Be sure that you adhere to these limits; otherwise, you will need to edit your abstract accordingly.
- 3) Written as **one paragraph**, and should **not contain** displayed **mathematical equations or tabular material**.
- 4) Should include **three or four different keywords or phrases**, as this will help readers to find it. It is important to avoid over-repetition of such phrases as this can result in a page being rejected by search engines.
- 5) Ensure that your abstract **reads well and is grammatically correct**.



Paper Structure

Good vs. Bad Abstract

The objective of this paper was to propose a human expert-based approach to electrical peak demand management. The proposed approach helped to allocate demand curtailments (MW) among distribution substations (DS) or feeders in an electric utility service area based on requirements of the central load dispatch center. Demand curtailment allocation was quantified taking into account demand response (DR) potential and load curtailment priority of each DS, which can be determined using DS loading level, capacity of each DS, customer types (residential/commercial) and load categories (deployable, interruptible or critical). Analytic Hierarchy Process (AHP) was used to model a complex decision-making process according to both expert inputs and objective parameters. Simulation case studies were conducted to demonstrate how the proposed approach can be implemented to perform DR using real-world data from an electric utility. Simulation results demonstrated that the proposed approach is capable of achieving realistic demand curtailment allocations among different DSs to meet the peak load reduction requirements at the utility level.

Vs

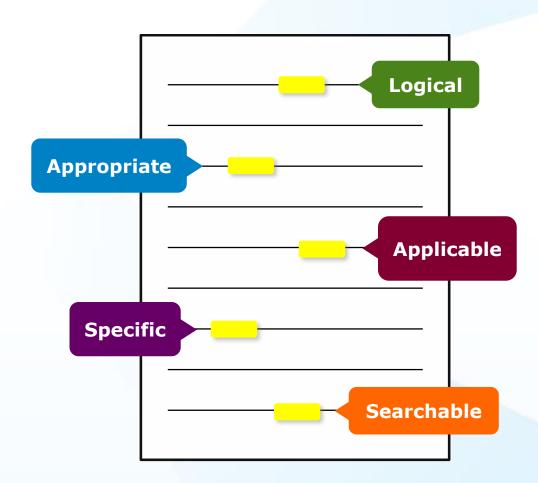
This paper presents and assesses a framework for an engineering capstone design program. We explain how student preparation, project selection, and instructor mentorship are the three key elements that must be addressed before the capstone experience is ready for the students. Next, we describe a way to administer and execute the capstone design experience including design workshops and lead engineers. We describe the importance in assessing the capstone design experience and report recent assessment results of our framework. We comment specifically on what students thought were the most important aspects of their experience in engineering capstone design and provide quantitative insight into what parts of the framework are most important.

First person, present tense
No actual results, only describes the organization of the paper



Paper Structure Keywords

Use in the Title and Abstract for enhanced Search Engine Optimization





IEEE Keywords

Bit rate, Decoding, Encoding, Parallel processing, Video coding

Authors Keywords

High Efficiency Video Coding (HEVC), parallel programming, video coding

INSPEC: Controlled Indexing

parallel processing, video coding

INSPEC: Non-Controlled Indexing

12-core system, H.264-advanced video coding, HEVC parallelization approaches, OWF, WPP, frequency 3.33 GHz, high efficiency video coding, overlapped wavefront, parallel efficiency, parallel friendliness, parallel scalability, parallelization proposals, tiles, wavefront parallel processing



Keywords link to potential reviewers

Keywords should be taken from the <u>taxonomy</u> provided in ScholarOne Manuscripts. <u>Using the keywords from the keyword list is essential to the review process because ScholarOne Manuscripts links them to names of potential reviewers who are associated with that area of expertise, thereby expediting the review process. We encourage all users to include keywords as part of their account information. If you currently do not have keywords included as part of your account information, you may add them by clicking the "edit your information" button on the main menu. Scroll down the page until you reach the "keywords" box. You may then select the keywords that apply to you from the list provided.</u>

https://www.computer.org/web/peer-review/journals#Length of Review Process



Paper Structure Introduction

- A description of the problem you researched
- It should move step by step through, should be written in present tense:

Generally known information about the topic

Prior studies'
historical
context to your
research

Your hypothesis and an overview of the results

How the article is organized

- The introduction should <u>not be</u>
 - Too broad or vague
 - More then 2 pages



Paper Structure Methodology

- Problem formulation and the processes used to solve the problem, prove or disprove the hypothesis
- Use illustrations to clarify ideas, support conclusions:

Tables

Present representative data or when exact values are important to show



Figures

Quickly show ideas/conclusions that would require detailed explanations



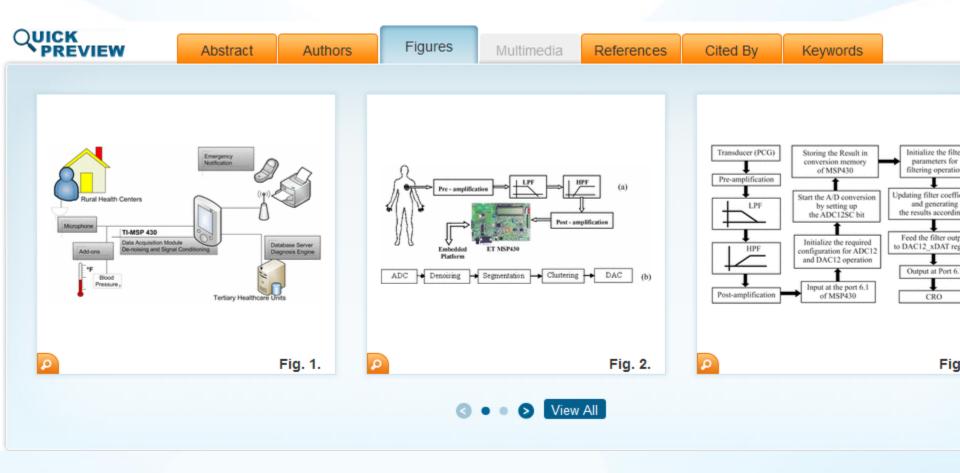
Graphs

Show relationships between data points or trends in data



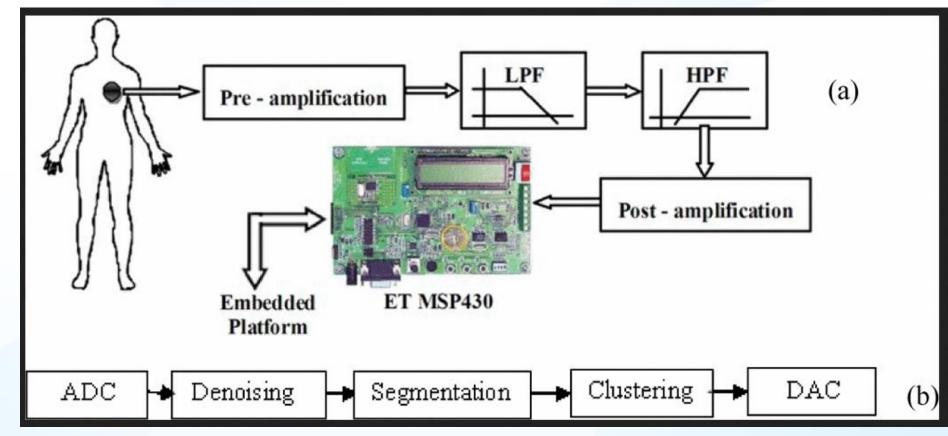


Downloadable figures from the HTML version on IEEE Xplore





Downloadable figures from the HTML version on IEEE Xplore





Equations in TeX Source in HTML version

▼ TeX Source

```
 $\eqalignno{\{\rm\ HS\}_{\{\rm\ recover\}} \& \|=\| \left(1 - \{E\eft\{x_{\{\rm\ HS\}}^2 \setminus \{rm\ reduct)\} \right} - E\eft\{\{y^2 \setminus \{rn\ right\}\} \right} \right) }
```

and NOISE reduction are computed in terms of percentages (see Table 1)

$$\text{HS}_{\text{recover}} = \left(\frac{1 - E\{x_{\text{HS}}^{2}(n)\} - E\{y^{2}(n)\}}{E\{x_{\text{HS}}^{2}(n)\}}\right) \times 100\%$$

$$\text{NOISE}_{\text{reduction}} = \left(\frac{E\{x_{\text{hs_noi}}^{2}(n)\} - E\{y^{2}(n)\}}{E\{x_{\text{hs_noi}}^{2}(n)\}}\right) \times 100\%$$

$$E\{x_{\text{hs_noi}}^{2}(n)\}$$



Paper Structure Results/discussion

Demonstrate that you solved the problem or made significant advances

Results: Summarized Data

- Should be clear and concise
- Use figures or tables with narrative to illustrate findings

Discussion: Interprets the Results

- Why your research offers a new solution
- Acknowledge any limitations

the SC algorithm over the whole range of w values increase to 3-4 K, except for the TIGR: to database, with an RMSE of 2 K. This last result is explained by the w distribution, which is biased toward low values of w in this database. When only atmospheric profiles with to values lower than S g - cm - 2 are selected, the SC algorithm provides RMS around 1.5 K, with almost equal values of bias and standard deviation, around 1 K in both cases (with a negative bias, thus the SC underestimates the LST). In contrast, when only we values higher than 3 g - cm⁻² are considered, the SC algorithm. provides RMSEs higher than 5 K. In these cases, it is preferable to calculate the atmospheric functions of the SC algorithm directly from (3) rather than approximating them by a polynomial fit approach as given by (4).

V. DISCUSSION AND CONCLUSION The two Landsat-S TIR bands allow the intercomparison

of two LST retrieval methods based on different physical such as the SC (only one TIR band required) fams (two TIR bands required). Direct inversion e transfer equation, which can be considered orithm, is assumed to be a "ground-truth" **Discussion** and L_d) is accurate enough. The SC algoin this letter is a continuation of the previous SC veloped for Landsat-4 and Landsat-5 TM sensors, ne ETM+ sensor on board the Landsat-7 platform [9], and it could be used to generate consistent LST products from the historical Landsat data using a single algorithm. An advantage of the SC algorithm is that, apart from surface emissivity, only water vapor content is required as input. However, it is expected that errors on LST become unacceptable for high water upper contents (e.g., > 3 g \cdot cm⁻²). This problem can be purify solved by computing the atmospheric functions directly from τ , L_{∞} , and $L_{\mathcal{L}}$ values [see (5)], or also by including air temperature as input [15]. A main advantage of the SW algorithm is that it performs well over global conditions and, thus, a wide range of water vapor values; and that it only requires water vapor as input (apart from surface emissivity at the two TIR bands). However, the SW algorithm can be only applied to the new Landant-S TIRS data, since previous TM/ETM sensors only had one TIR band.

The LST algorithms presented in this letter were tested with simulated data sets obtained for a variety of global atmospheric conditions and surface emissivities. The results showed RMSE values of typically less than 1.5 K, although for the SC algorithm, this accuracy is only achieved for w values below 9 g - cm⁻². Algorithm teeting also showed that the SW errors are lower than the SC errors for increasing water vapor, and vice versa, as demonstrated in the simulation study presented in Sobrino and Jiménez-Muñoz [18]. Although an extensive validation exercise from in sits measurements is required to assess the performance of the two LST algorithms, the results obtained for the simulated data, the sensitivity analysis, as well as the previous findings for algorithms with the same mothemotical structure give confidence in the algorithm accuracies

Results

[4] VI. Nastas and M. Anderson. "Advances in thermal infrared negative sensing for land surface modeling," Agric. Porest Maleorol., vol. 149, no. 12,

pp. 2073-2081, Dec. 2009.

[3] X.-L. Li, R.-H. Timp, H. Wu, H. Ren, G. Yin, Z. Whn, I. F. Trign, and I. A. Sobrino, "Satellite-derived land surface temperature: Connect. status and perspectives," Servate Sens. Environ., vol. 131, pp. 14-37,

[8] Z.-L. Li, H. Wu, N. Wang, S. Qiu, J. A. Sobrino, Z. Wan, R.-H. Tang, and G. Yan, "Land surface emissivity retrieval from schellin drin," Int. J. Remote Sear., vol. 54, no. 9110, pp. 5064-5127, 2015.

[7] A. M. Miko, "Three decades of Landact instruments," Photo

 [7] A. N. Stein, I rive decides of Limited materials, Poccognition and Remote Sease, vol. 62, no. 7, pp. 659-652, Jul. 1997.
 [8] S. A. Eurel, J. R. Schett, F. D. Pallaconi, D. L. Helder, S. S. Hook, R. L. Markhorn, G. Chandler, and E. M. O'Donnell, "Londout TM and ETM+ thermal band calibration," Gas. J. Sewaris Sess., vol. 29, no. 2, pp. 141–152, 2005. [F] N. C. Resinac-Marico, J. Cristifoul, J. A. Sobrino, G. Shria, M. Ninyamia

and X. Poss, "Revision of the single-channel algorithm for land surface temperature retrieval from Lundar thermal-inflated data," IEEE Trans.

General Service Serv., vol. 47, no. 1, pp. 219–349, lbn. 2009.

[10] L. M. McMülle, "Estimation of sea surface temperatures from two infrared window measurements with different absorption," J. Geophys. Serv., vol. 90, no. 34, pp. 5113-5117, 1975. [11] J. A. Schrino, Z.-L. Li, M. P. Stoll, and E. Backer, "Multi-channel and

multi-angle algorithms for setimating sea and land surface temperature with ATSR data," Int. J. Remote Sens., vol. 17, no. 11, pp. 2089-0114,

[12] J. C. Traillaco-Marico and J. A. Sobrino, "Spih-window conflicients for land surface temperature retrieval from low-custorion thermal infrared sensors," *IEEE Geneti. Servets Serv. Lett.*, vol. 5, no. 4, pp. 806–609, Oct. 2008.

[17] A. Back, G. R. Anderson, R. K. Asharya, J. R. Chetrynd, L. S. Bernetsin, E. R. Shetle, M. W. Mothert, and S. M. Adiso-Golden, MODITRAWA Direc's Moreaul. Homsonn AFE, MA, USA: Air Potce Res. Lab., 1999. [14] A. M. Buldridge, S. J. Hook, C. I. Grove, and G. Rivera, "The ASTER.

spectral Fibrary variation 2.0," Semante Steat. Electron., vol. 113, no. 4, pp. 711-715, Apr. 2009.
[15] N. Criseffeal, J. C. Jimánan-Medice, J. A. Sebrino, M. Ninyerola, and

[27] C. Gerrento, C. Communication in Standard Services, Services and Association and Services and Service C. Dalaci, R. Dengoni, M. Paeries, A. f. Geer, L. Halmberger S. R. Healy, H. Haraboch, E. V. Hölm, L. Indones, R. Kullberg, M. Kobler M. Motricandi, A. F. McNally, E. M. Mange-Sanc, J.-f. Monorette, R.-K. Fark, C. Peuber, P. de Rossey, C. Toroloto, J.-N. Thépont, and F. Vitar, "The ERA-Inferior remarks in Configuration and performance of the data assimilation system," Q. J. R. Material, Soc., vol. 137, no. 656, pp. 555-697, 2011.
C. Marter, C. Durfer-Alarofe, J. C. Resinez-Minfox, and J. A. Sobrino

"Global Atmospheric Profiles from Recoulysis Information (GAFRI): A new detaset for forward simulations in the thermal infrared region, "MEE Press. George, Revote Seer., 2014, submitted for publication.

[15] J. A. Sobrino and J. C. Renina-Multice, "Land surface temperature settlevel from thermal infrared data: An assessment in the content of the surface processes and scorystem changes through response analysis (SPECTEA) mission," J. Geophys. Sec., vol. 110, no. D06, p. D1608,



Paper Structure Conclusion

- Explain what the research has achieved
 - As it relates to the problem stated in the Introduction
 - Revisit the key points in each section
 - Include a summary of the main findings, important conclusions and implications for the field
- Provide benefits and shortcomings of:
 - The solution presented
 - Your research and methodology
- Suggest future areas for research





Paper Structure References

- Support and validate the hypothesis your research proves, disproves or resolves
- There is no limit to the number of references
 - But use only those that directly support our work
- Ensure proper author attribution
 - Author name, article title, publication name, publisher, year published, volume, chapter and page number
 - IEEE journals generally follow a citation numbering system

1538

Properly

cited material

We then have

$$(P_t^{a,+} + P_t^{a,-})^2 - (P_t^{a,+} - P_t^{a,-})^2 + 4P_t^{a,+}P_t^{a,-}$$

 $< (\hat{P}_t^{a,+} - \hat{P}_t^{a,-})^2 + 4\hat{P}_t^{a,+}\hat{P}_t^{a,-}$
 $- (\hat{P}_t^{a,+} + \hat{P}_t^{a,-})^2.$ (32)

Since $P_i^{h,+} - P_i^{h,-} = P_i^{h,+} - P_i^{h,-}$, we then have $P_i^{h,+} < P_i^{h,+}$, and $P_i^{h,-} < P_i^{h,-}$. Because the operational cost is an increasing function of $\{P_i^{h,+}, P_i^{h,-}\}$, we obtain that

$$c_{n/m}(P_t^{s,+}, P_t^{s,-}) < c_{n/m}(\hat{P}_t^{s,+}, \hat{P}_t^{s,-}).$$
 (33)

Therefore the optimal pair $\{P_i^{h,+},P_i^{h,-}\}$ must satisfy that $P_i^{h,+}P_i^{h,-}=0$, i.e., only one of $P_i^{h,+},P_i^{h,-}$ can be non-zero.

REFERENCES

- [1] "Renewables: Energy You can Count on," Tech. Rep. Union of Concerned Scientists, 2013.
 S. Collier, "Ten street to a smarter and "WWW led. April May, vol. 16.
- so. 2, pp. 62-68, 2010.
- [3] J. A. Turnet, "A realizable mn-awable-energy future," Sci., vol. 283, no. 5428, pp. 687–689, 1999.
- [4] "Exploration of High-Pesetration Renewable Electricity Futures," Tech. Rep. National Renewable Energy Lab., 2012.
- [5] T. Wiedmann and J. Minn, A Digitation of Corbon Footprine. Hasp-page, NY, USA: Nova Science, 2008.
- [5] J. Carracco, L. Franquelo, J. Bialastewicz, E. Galvae, R. Guisado, M. Posts, J. Leou, and N. Moreno-Alfonso, "Power-electronic systems for the grid integration of renewable energy sources: A survey," IEEE Trans. Ind. Electron., vol. 53, no. 4, pp. 1902–1916, 2006.
- Trans. Ind. Allicoron., vol. 53, no. 4, pp. 1002–1016, 2006.

 [7] H. Brahlm, A. Ilinoa, and J. Perron, "Desigy stronge systems —characteristics and comparisons," Renewable Sunstituable Energy Sen., vol. 12, no. 5, pp. 1221–1250, 2000.
- [8] J. Clarcia-Conzalez, R. de la Moela, L. Nazine, and A. Gonzalez, "Sto-chastic joint optimization of wind generation and pumped-storage units in an electricity marker," IEEE Trans. Power Syst., vol. 23, no. 2, pp. 460–468, 2008.
- [9] T. D. Nguyen, K.-J. Tamp, S. Zhang, and T. D. Nguyen, "On the moding and control of a novel flywhool energy storage system," in Proc. IEEE, 2010, pp. 1395–1401.
 Zhoe, T. Bhatischarya, D. Tran, T. Siew, and A. Khambadkone,
 - Chou, T. Bhattacharya, D. Tran, T. Siew, and A. Khambadtone, e-posite energy storage system involving battery and ultracapacitor ratio energy management in microgrid applications," IEEE Conference, vol. 26, no. 3, pp. 923–930, 2011.
 - Clariron, vol. 26, no. 3, pp. 923–930, 2011.

 and J. F. Miller, "Key challenges and roomt progress in
 A, fiel cells, and Sydrogen tomage for clean energy systems,"
 over Sources, vol. 193, no. 1, pp. 73–80, 2000.
 acros and D. Iridal, "Energy Sorage and its use with intermitates
 exchals energy," ISUE Trans. Beargy Conversion, vol. 19, no. 2, pp.
 41–448, 2034.
- [13] K. O. Vosburgh, "Compressed air energy storage," J. Shergo, vol. 2, no. 2, pp. 106–112, 1978.
- [14] C. Abbey and G. Josa, "Supercapacitor energy storage for wind energy applications," *IEEE Trans. Ind. Appl.*, vol. 43, no. 3, pp. 769–776, 2007.
 [15] P. Brown, J. P. Loose, and M. Matos, "Optimization of purposed storage."
- [15] P. Brown, J. P. Lopen, and M. Matos, "Optimization of pumped storage capacity in an isolated power system with large renewable penetration," *IEEE Trans. Power Syst.*, vol. 23, no. 2, pp. 523–531, 2008.
- [16] C. Abbey and G. Joos, "A stochastic optimization approach to rating of energy storage systems in wind-dissell isolated grids," IEEE Trans. Private Syst., vol. 24, no. 1, pp. 418–426, 2009.
- [17] Y. Zhang, N. Gatin, and G. Giannakin, "Robust energy management for microgride with high-penetration renewables," *IEEE Trans. Sus*tainable Energy, vol. 77, no. 99, pp. 1–10, 2013.

BEER TRANSACTIONS ON SMART GRID, VOL. 5, NO. 4, JULY 2014

- [13] S. Boyd, N. Parlich, E. Chu, B. Peleato, and J. Eclorieiz, "Distributed opterization and statistical learning via the alternating direction method of realispliers," Foundations Trends Mach. Learning, vol. 3, no. 1, pp. 1–122, 2010.
- [19] G. Calaffore and M. Campi, "The someto approach to robust control design," *IEEE Trans. Autom. Contr.*, vol. 51, no. 5, pp. 742–752, 2006.
 [20] A. Shapiro, D. Destribeva, and A. Russcrynski, Lectures on Stochastic Programming: Modeling and Theory. Philadelphia, NJ, USA: SIAM.
- [21] Y. Zhang, N. Gainis, and G. Giannakis, "Risk-constrained energy management with multiple wind farms," in Proc. IEEE PISS ISCIT, Feb.
- 2013, pp. 1-6.
 [22] Y. Zhang, N. Gatsis, V. Kekaton, and G. Giannsalda, "Risk-aware management of distributed energy resources," in Proc. Set. Conf. Digital
- Signal Process, Int. 2013, pp. 1–5.

 [23] P. Yang and A. Neboni, "Hybrid energy storage and generation planning with large reservable penetration," in IEEE Int. Morbibop Com-
- patat Adv. Afrikit-Sessor Adaptive Process., Dec. 2013, pp. 1-4.
 [24] EPKI, "Electricity Bassgy Storage Technology Options: A White Paper Primer on Applications, Costs, and Henefits," Tech. Rep. EPKI, Palo Alto, CA, USA, 2010.
- [25] National Solar Radiation Data Base, [Online]. Available: http://redc
- nest gavisolaciold data/rands/ [26] S. Witcox, National Solar Radiation Database 1991 – 2010 Update User's Manual, 2012.
- [27] EFRI, "Renewable Energy Technical Assessment Guide TAG-RE-2006," Tech. Rep. EFRI, Pulo Alto, CA, USA, 2007.
 [28] EFCOT Nearly Load Data Archive [Online]. Available: http://www.
- [28] ERCOT Hourly Load Data Archive [Online]. Available: http://www.scot.com/gridinfo/load/load_bia/
 [29] M. Onet and S. Bord, CVP. Mediah Software for Distributed Convention.
- [29] M. Umer and S. Doyd, C.F.C. Memab Seyware for Exceptioned Control Programming, Version 2.0 Beta 2012 [Online]. Available: http://cvicr. com/eve
- [30] "MISO Daily Report," 2011, Electric Power Markett: Midwest (MISO), PERC [Online]. Available: http://www.ferr.gov/market-over-sight/mkt-electric/midwest/miso-archives.asp
- [31] "CAISO Daily Report," 2011, Electric Power Markets: California (CAISO), PERC [Online]. Available: http://www.ferc.gov/market-oversight/mik/-electric/california/calso-archives.asp



Feng Yang (S'11) received the II-Sc. degree is electrical engineering from University of Science and Technology, Anhai, Chica in 2009, and the M-Sc. and Ph.D. degrees in electrical engineering from Washington University in St. Louis, R. Louis, MO, USA, in 2011 and 2014, respectively. His Ph.D. artisor in Dr. Arpy Nelsons.

His research interests include statistical signal processing, optimization, machine learning, and compressive sensing, with applications to amart with



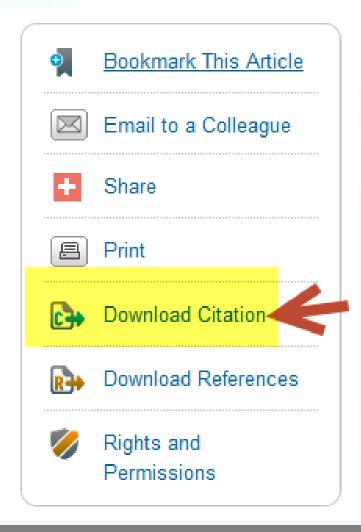
Arye Neharai (S'10-M'E3-SM'90-B'94) received the B.S. and M.S. degrees from the Technico, Haith, basel, and the Ph.D. degree from Stanford University, Stanford, CA, USA.

He is the Eugene and Martin Lohman Professor and Chair of the Preston M. Cheen Department of Electrical and Systems Engineering (1851); at Washington University in St. Louis (WUSTL), St. Louis, MO, USA. Earlier, he was a facely as ember at Talis University and the University of Illinois at Chicago.

Dissecutive and the University of Illinois at Chicago. Dr. Nelsons served as Educos-in-Chica E



Working with Citation Management Software





Working with Citation Management Software

DOWNLOAD CITATIONS

Include:

- Citation Only
- Citation & Abstract

Format:

- Plain Text
- BibTeX
- Refworks
- EndNote, ProCite, RefMan

Download Citation

Cancel



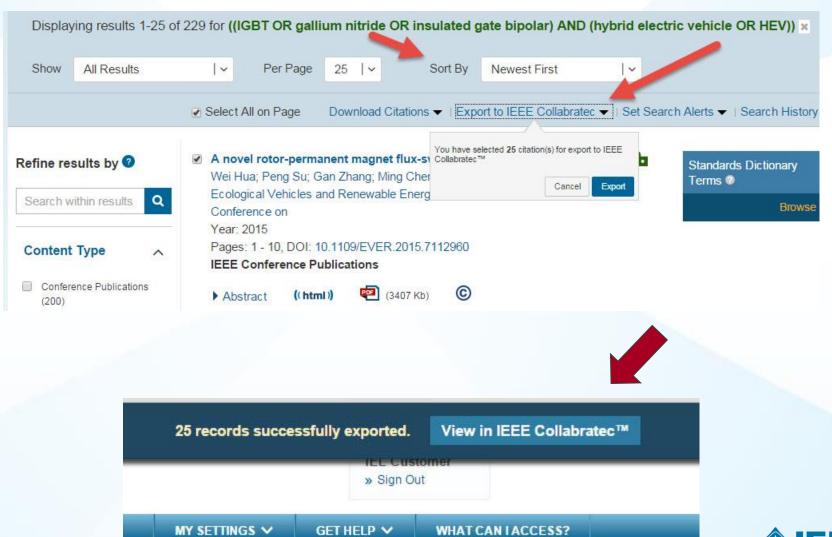
Working with Citation Management Software

Kolb,·S.;·Stolle,·R.,·"Improved·image·quality·in·multistatic· microwave·gauging,"·in·*Microwave· Symposium·Digest·(MTT),·2011·IEEE·MTT-S·International·*,·vol.,·no.,·pp.1-1,·5-10·June·2011• doi:·10.1109/MWSYM.2011.5973259•

URL: URL: http://ieeexplore.ieee.org/stamp/stamp.jsp?tp=&arnumber=5973259&isnumber=5972556

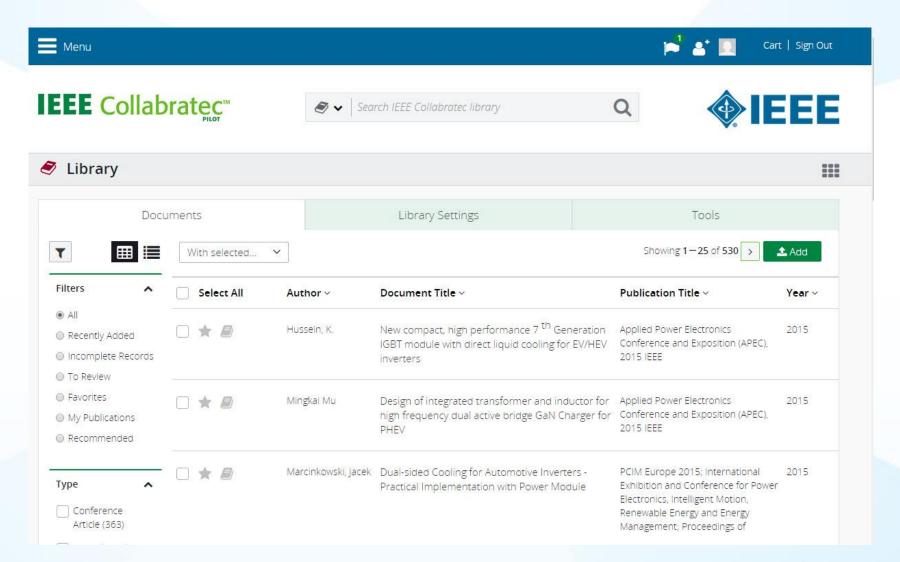


Organize Your Research with IEEE Collabratec





Export Documents to Collabratec





Writers last task once all sections are written:

- How do they fit together?
- Does each section perform its appointed task?
- Is the order logical?
- Do the ideas flow together? Is it easy to read?
- Does the same material appear more than ones?
- Can it be clearer?
- Is there enough detail?



Review

Review Process

1 day Step1 Sent to EiC Step 2 3 days Sent to AE 6 days Step 3 Reviews contact 6 days 45 days Step4 Step9 Reviews accept 30 days Step 5 30 days AE step 6 7 days Major revision Minor revision reject accept Author Author FIC Step8 Step7 60 days straight accept Paper accepted Step 10 90 days accept with minor revision 155 days accept with major revision 184 days accept with major and minor Step 11 Publication (30 days to final) (3 months to publish) Step 12

Paper received

0 days

e.g. IEEE
Transactions on
Information
Technology in
Biomedicine

Audience

What IEEE editors and reviewers are looking for

- Content that is appropriate, in scope and level, for the journal
- Clearly written original material that addresses a new and important problem
- Valid methods and rationale
- Conclusions that make sense
- Illustrations, tables and graphs that support the text
- References that are current and relevant to the subject



Audience

Why IEEE editors and reviewers reject papers

- The content is not a good fit for the publication
- There are serious scientific flaws:
 - Inconclusive results or incorrect interpretation
 - Fraudulent research
- It is poorly written
- It does not address a big enough problem or advance the scientific field
- The work was previously published
- The quality is not good enough for the journal
- Reviewers have misunderstood the article



Ethics



Ethics

Types of misconduct

Conflict of Interest

 A financial or other relationship with the publication at odds with the unbiased presentation of data or analysis

Plagiarism

 Copying another person's work word for word or paraphrasing without proper citation

Author Attribution

 Must be given if you use another author's ideas in your article, even if you do not directly quote a source

Author involvement/contributions

- Include any and all who have made a substantial intellectual contribution to the work
- Do not include minor contributors



Ethics

Ethical publishing

Duplication, Redundancies & Multiple Submissions

- Author must submit original work that:
 - Has not appeared elsewhere for publication
 - Is not under review for another refereed publication
 - Cites previous work
 - Indicates how it differs from the previously published work
 - Authors MUST also inform the editor when submitting any previously published work



Refer to our Tips Sheet http://www.ieee.org/publications standards/publications/authors/plagiarism and multiple submissions.pdf



Open Access Publications



Types

- Traditional Journals –
 Users/Libraries pay for access
- Open Access Journals –
 Author pays article costs, free download
- Hybrid Journals –

Most articles are traditional, some are open access (author preference)



http://open.ieee.org/

IEEE OPEN

search

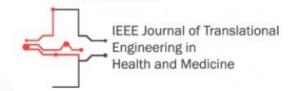


First Fully Open Access Topical Journals



IEEE Journal of Electron Devices Society





Editors in Chief



Fabrizio Lombardi, IEEE Transactions on Emerging Topics in Computing



Carmen S. Menoni, IEEE Photonics Journal



Renuka P. Jindal, IEEE Journal of Electron Devices Society



Clifford Dacso, IEEE
Journal of Translational
Engineering in Health &
Medicine



Atam P. Dhawan, IEEE Journal of Translational Engineering in Health and Medicine



Since 2014/15 – Four New OA Topical Journals

IEEE Exploratory Solid-State Computational Devices and Circuits

Multi-disciplinary research in solid-state circuits

IEEE Life Sciences Letters

 Articles that apply methods of quantitative analysis to biological problems at the molecular, cellular, organ, human and population levels

IEEE Nanotechnology Express

Novel and important results on engineering at the nanoscale

IEEE Power and Energy Technology System Journal

Practice-oriented articles focusing on the development, planning, design, construction, maintenance, installation and operation of equipment, structures, materials and power systems

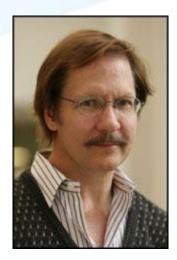
Since 2013:

IEEE Access

practical innovations **open** solutions

- A broad-scope "Megajournal" to cover multi-disciplinary topics that don't naturally fit into one of IEEE's existing primary transactions or journals
- Online-only archival publication: no page limits; supporting data and videos encouraged
- Applications-oriented articles such as interesting solutions to engineering or information system design challenges, practical experimental techniques, manufacturing methods, etc.
- Rapid, yet thorough, binary peer-review and publication process with submissions judged on technical substance and presentation quality
- Readers will evaluate work through comments and usage metrics, which are updated frequently and displayed with the abstract of each paper published





Dr. Michael Pecht, Editor in Chief



OA Models Bridge Author Needs

IEEE's Open Access Publishing Options

	What it is	Topics covered	Why publish here?
Fully OA Topical Journals	Online, peer-reviewed journals focused on niche topics.	Photonics, Emerging Computing Topics, Translational Engineering, Electron Devices.	Benefit from a larger potential audience with traditional topic focus areas for each journal, as well as a faster time to publish for some journals.
Hybrid Journals	100+ traditional journals with an OA option.	All IEEE fields of interest.	Gives authors the benefit of multiple journals with established Impact Factors; publish in print and online.
IEEE Access practical innovations; open solutions	Online, peer-reviewed "megajoumal".	Practical research across ALL IEEE fields of interest, covered by established thought leaders.	Meets demand for practical information that can bring new products and innovations to market faster, or that doesn't neatly fit into a single topic area; a rapid, binary peer-review process ends in acceptance or rejection.



Self-Archiving policy

■ IEEE allows authors to deposit the accepted (not final) version of their paper (available through the Author Gateway) to their institutional or funding repository, or to post it on their personal websites.

Our full deposition policy can be found here: http://www.ieee.org/publications_standards/publications/rights/paperversionpolicy.html



IEEE Author Tools



Locate and Use IEEE Author Tools

http://www.ieee.org/publications_standards/publications/authors/authors_journals.html











IEEE offers a suite of tools to help authors prepare their manuscript and find the right publication outlet.

Our package of tools is unique among scholarly publishers.













Author Tool: Article Templates

> REPLACE THIS LINE WITH YOUR PAPER IDENTIFICATION NUMBER (DOUBLE-CLICK HERE TO EDIT) <

Preparation of Papers for IEEE TRANSACTIONS and JOURNALS (December 2013)

First A. Author, Fellow, IEEE, Second B. Author, and Third C. Author, Jr., Member, IEEE

Abstract—These instructions give you guidelines for preparing papers for IEEE Transactions and Journals. Use this document as a template if you are using Microsoft Word 6.0 or later. Otherwise, use this document as an instruction set. The electronic file of your paper will be formatted further at IEEE. Paper tides should be uritten in uppercase and lowercase letters, not all uppercase. Avoid writing long formulas with subscripts in the tide; short formulas that identify the elements are fine (e.g., "NdFe-B"). Do not write "(Invited)" in the tide. Full names of authors are preferred in the author field, but are not required. Put a space between authors' initials. Define all symbols used in the abstract. Do not delete the blank line immediately above the abstract; it sets the footnote at the bottom of this column.

Index Terms—Enter key words or phrases in alphabetical order, separated by comman. For a list of suggested keywords, send a blank e-mail to https://www.isea.org/organizations/pubs/ani-prod/keywe198.txt

I. INTRODUCTION

THIS document is a template for Microsoft Word versions fo. or later. If you are reading a paper or PDF version of this document, please download the electronic file, TRANS-JOUR.DOC, from the IEEE Web site at https://www.ieee.org/web/publications/unthorw/transini/index.html 30 you can use it to prepare your manuscript. If you would prefer to use LATEX, download IEEE's LATEX style and sample files from the same Web page. Use these LATEX files for formatting, but please follow the instructions in TRANS-JOUR.DOC or TRANS-JO

If your paper is intended for a conference, please contact your conference editor concerning acceptable word processor formats for your particular conference.

This paragraph of the first footnote will contain the obste on which you used interesting your paper for review. It will also contain support information, including sponsor and financial support acknowledgment. For example, "This work was supported in part by the U.S. Department of Commerce under Grant BS132450".

The next few paragraphs should contain the authors' current affiliations, including current address and c-mail. For example, F. A. Author is with the National Institute of Standards and Technology, Boulder, CO 80305 USA (c-mail: authors) boulder aint;pov).

S. B. Author, Jr., was with Rice University, Houston, TX 77005 USA. He is now with the Department of Physics, Colorado State University, Fort Collins, CO 80513 USA (c-mail: author@lamar.colorate.edu).

T. C. Author is with the Electrical Engineering Department, University of Colorado, Boulder, CO 80309 USA, on leave from the National Research Institute for Metals, Tauloubs, Japan (e-mail: author@nrim.go.jp).

II. GUIDELINES FOR MANUSCRIPT PREPARATION

When you open TRANS-JOUR DOC, select "Page Layout" from the "View" menu in the menu bar (View | Page Layout), (these instructions assume MS 6.0. Some versions may have alternate ways to access the same functionalities noted here). Then, type over sections of TRANS-JOUR DOC or cut and paste from another document and use markup styles. The pull-down style menu is at the left of the Formatting Toolber at the top of your Word window (for example, the style at this point in the document is "Text"). Highlight a section that you want to designate with a certain style, then select the appropriate name on the style menu. The style will adjust your fonts and line spacing. Do not change the font sizes or line spacing to squeeze more text into a limited number of pages. Use italics for emphasis; do not underline.

To insert images in Word, position the cursor at the insertion point and either use Insert | Picture | From File or copy the image to the Windows clipboard and then Edit | Paste Special | Picture (with "float over text" unchecked).

IEEE will do the final formatting of your paper. If your paper is intended for a conference, please observe the conference page limits.

A. Abbreviations and Acronyms

Define abbreviations and acronyms the first time they are used in the text, even after they have already been defined in the abstract. Abbreviations such as IEEE, SI, ac, and dc do not have to be defined. Abbreviations that incorporate periods should not have spaces: write "C.N.R.S.," not "C. N. R. S." Do not use abbreviations in the title unless they are unavoidable (for example, "IEEE" in the title of this article).

B. Other Recommendations

Use one space after periods and colons. Hyphenate complex modifiers: "zero-field-cooled magnetization." Avoid dangling participles, such as, "Using (1), the potential was calculated." [It is not clear who or what used (1).] Write instead, "The potential was calculated by using (1)," or "Using (1), we calculated the potential."

Use a zero before decimal points: "0.25," not ".25." Use "cm²," not "cc." Indicate sample dimensions as "0.1 cm × 0.2 cm," not "0.1 × 0.2 cm." The abbreviation for "seconds" is "s," not "sec." Use "Whym" or "webers, per square meter," not "yebers/m²." When expressing a range of values, write "7 to 9" or "7-9." not "7-9." not "7-9."



Author Tool: Reference Preparation Assistant

IEEE Author

IEEE Reference Preparation Assistant



Administration

Help Login

The IEEE Reference Preparation Assistant is an automated tool for use by authors to validate references against both the IEEE Xplore and CrossRef databases in order to ensure successful on-line linking. This tool should be used before submitting an article to IEEE. Please log in to begin.

Enter your details to log in			
All information is required			
First name			
Last name			
Email address			
	CONTINUE		



Author Tool: PDF Checker

IEEE PDF Checker

Upload File

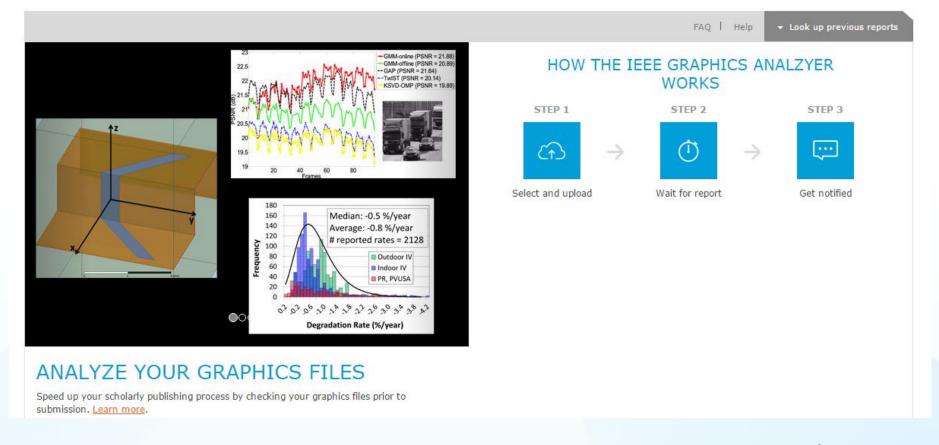
Paper Title:				
IEEE Publication Title:	Aerospace & Electronics Systems Magazine, IEEE ▼			
File:	Browse			
Upload File				



Author Tool: Graphics Analyzer









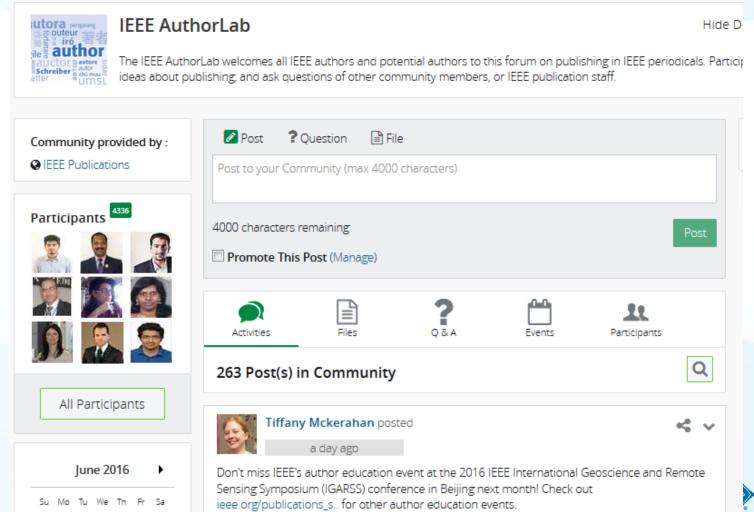
More Graphics Help

Detailed guidance on graphics is available at http://www.ieee.org/publications_standards/publications/authors_journals.html#sect2.

The Graphics Help Desk (graphics@ieee.org) works one-on-one with authors to improve existing graphics or create custom new graphics.

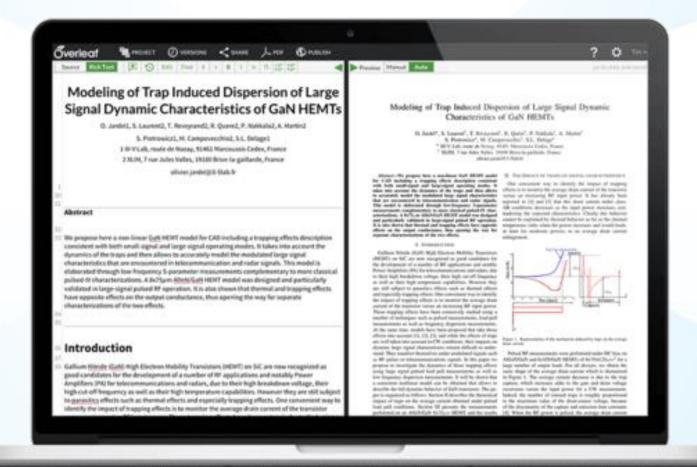


Use AuthorLab in IEEE Collabratec for additional support and help





Benefit of IEEE Collabratec: Free Overleaf account







Open Researcher and Contributor ID (ORCID)

ORCID is a unique, persistent identifier for authors that helps them:

- Ensure their work is discoverable and connected to them throughout their career (including moves and name changes)
- Minimize the time spent entering repetitive information for manuscript submissions and grant applications
- > Eliminate name ambiguity and ensure proper attribution

IEEE will require ORCIDs for all corresponding authors effective July 2016.





Throughout the process...Refer here early and often – IEEE Author Digital Tools

Author Digital Tools

 IEEE Publications Menu

Publications Home

Publications News

- Publication Types
- Publishing Tools & Services
- Reprints, Rights & Permissions

Advertising in IEEE Publications

- Publications Board
- Author Resources

Contact IEEE Publishing

Author FAQs

DIGITAL TOOLS

Below are information and tools to assist with all stages of publishing with IEEE.

On this page:

- > Preparing your article
- Preparing your graphics and multimedia materials
- > Guidelines for article submission
- > Post-acceptance procedures
- > Post-publication procedures
- > Frequently asked questions

Preparing your article

→ IEEE Publishing Policy

(PDF, 46 KB)

Important information for authors interested in publishing in IEEE Transactions, Journals, and Letters.

Register for an ORCID

Register for the persistent digital identifier that distinguishes you from every other researcher.

Overleaf Collaborative Authoring

IEEE has partnered with Overleaf to allow authors to collaborate, write articles, and share files.

> IEEE Style Manual

(PDF, 574 KB)

Editorial guidelines for IEEE Transactions, Journals, and Letters.

Keywords Suggested for Authors

(PDF, 326 KB)

Authors are encouraged to select keywords from this list. It comprises the first three hierarchical "levels" under each term-family (or branch) that is formed from the top-most terms of the IEEE Thesaurus. If you cannot find appropriate terms, you may add your own.

> Article Templates

Includes templates and instructions on how to prepare your papers for publication in IEEE Transactions and Journals.

Authorship

- Learn the benefits of publishing with IEEE
- View authorship workshop video for writing technical papers
- IEEE Publication Recommender

IEEE Open Access

IEEE Open Access delivers articles free of charge to readers worldwide.

Learn about IEEE Open Access

More Useful Links

Article Templates

Find appropriate templates for the publication you intend to publish in

Author Copyright Help

- > IEEE Rights & Permissions Department
- Download IEEE Copyright Form

(PDF,108 KB)

Contact IEEE Transactions, Journals and Letters

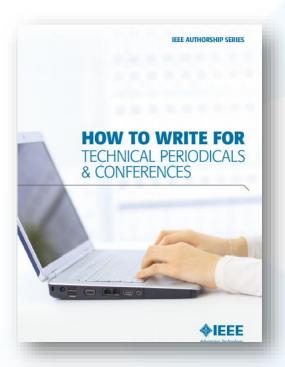
For general inquires or to request further information, email trans@ieee.org

For inquiries specific to graphics, email graphics@ieee.org



IEEE Author Guide Always Available

- Authors learn how to prepare, write, and submit quality technical articles
- Can be downloaded
- Includes embedded links to information, forms, etc.





For more information or to

download: http://www.ieee.org/publications_standards/publications/auth ors/publishing_benefits/index.html?WT.mc_id=pb_ben_pub



Contacts for Author Questions

Abstract & Indexing services	discoveryservices@ieee.org
Copyright policies	copyrights@ieee.org
Permissions and reuse	pubs-permissions@ieee.org
Posting articles in repositories	copyrights@ieee.org
Preparing figures	graphics@ieee.org
Reprints	reprints@ieee.org
Status report on article in production	Publication editor or trans@ieee.org
Subscriptions	customer-service@ieee.org



Useful articles on IEEE Xplore

- "Beginnings and endings: keys to better engineering technical writing" Pierson, M.M.; Pierson, B.L.,
- "Hints on writing technical papers and making presentations" Li, V.O.K.
- "How to Get Your Manuscript Published in this Transactions in Six Months or Less" Williams, Dylan F.

http://ieeexplore.ieee.org



Key sites to remember

Manuscript "How to write":

http://www.ieee.org/publications standards/publications/authors/author gui
de interactive.pdf

IEEE Author Tools <u>IEEE.org/go/authorship</u>

IEEE Conference Search and Calls for Papers:

http://www.ieee.org/conferences_events/index.html

IEEE Publication Recommender[™]

http://publication-recommender.ieee.org/home

IEEE Xplore: http://ieeexplore.ieee.org

IEEE Xplore information, training and tools:

http://www.ieee.org/go/clientservices

IEEE Journal Citation reports:

http://www.ieee.org/publications_standards/publications/journmag/journalcitations.html



Free Authorship videos on IEEE.tv

Speaker: Professor Saifur Rahman from Virginia Tech (VP of Pubs for IEEE's Power & Energy Society)

http://innovate.ieee.org/innovate/industry/academic/whats-new/newcontent/article/80448







THANK YOU!

Eszter Lukács

IEEE Client Services Manager - Europe

e.lukacs@ieee.org

Web: www.ieee.org/go/clientservices

